

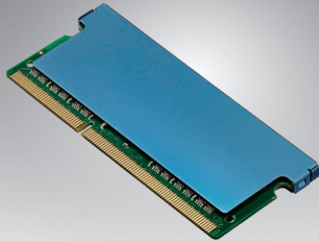
SQR-HS3N

Heatsink series

SQR-HS4N

Heatsink series

NEW



RoHS COMPLIANT 2002/95/EC CE FCC

Features

- Original Samsung, Micron DRAM IC adopted
- Data Transfer Rate: 1600 MT/s
- Heatsink attached
- Thermal sensor attached
- Fixed BOM

Specifications

| | |
|-----------------------|------------------|
| DDR Type | DDR3L |
| Pin / DIMM | 204pin SODIMM |
| Data Transfer Rate | 1600 MT/s |
| Golden Finger | 30u" |
| Capacity | 4GB/ 8GB |
| Power Supply | 1.35V / 1.5V |
| Operating Temperature | -40 ~ 85 °C |
| Dimensions (mm) | 67.6 x 30 ± 0.15 |

Ordering Information

| PN | Description |
|--------------------|---|
| SQR-HS3I-4G1K6SNLB | HEATSINK 204pin SODIMM DDR3L 1600 4GB 1.35v 512x8 (-40 ~ 85 °C) SAM |
| SQR-HS3I-8G1K6SNLB | HEATSINK 204pin SODIMM DDR3L 1600 8GB 1.35v 512x8 (-40 ~ 85 °C) SAM |
| SQR-HS3I4G1K6MNEPB | HEATSINK 204pin SODIMM DDR3L 1600 4GB 1.35v 512x8 (-40 ~ 85 °C) MIC |
| SQR-HS3I8G1K6MNEPB | HEATSINK 204pin SODIMM DDR3L 1600 8GB 1.35v 512x8 (-40 ~ 85 °C) MIC |

NEW



RoHS COMPLIANT 2002/95/EC CE FCC

Features

- Original Samsung DRAM IC adopted
- Data Transfer Rate: 2666/3200 MT/s
- Anti-sulfuration DRAM module
- Heatsink/Thermal sensor attached
- Fixed BOM

Specifications

| | |
|-----------------------|------------------------|
| DDR Type | DDR4 |
| Pin / DIMM | 260pin SODIMM with ECC |
| Data Transfer Rate | 2666/3200 MT/s |
| Golden Finger | 30u" |
| Capacity | 16GB ~ 32GB |
| Power Supply | 1.2V (1.26V~1.14V) |
| Operating Temperature | 0 ~ 85/-40 ~ 85 °C |
| Dimensions (mm) | 69.6 x 30 ± 0.13 |

Ordering Information

| PN | Description |
|--------------------|---|
| SQR-HS4I16G3K2SECB | Heatsink 240pin ECC SODIMM DDR4 3200 16GB 1.2v 1Gx8 (-40 ~ 85 °C) SAM |
| SQR-HS4I32G3K2SEAB | Heatsink 260pin ECC SODIMM DDR4 3200 32GB 1.2v 2Gx8 (-40 ~ 85 °C) SAM |
| SQR-HS4N16G3K2SECB | Heatsink 240pin ECC SODIMM DDR4 3200 16GB 1.2v 1Gx8 (0 ~ 85 °C) SAM |
| SQR-HS4N32G3K2SEAB | Heatsink 260pin ECC SODIMM DDR4 3200 32GB 1.2v 2Gx8 (0 ~ 85 °C) SAM |